ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® INDUSTRIES® INDUSTRIES®	ockburn, Illinois. A	Il rights reserved und ntions.	der both This docur level parts	nent is a declar , the declaratio	ation of the s	ubstances es all lowe	s within the manufactur er level materials for wl	er listed ite hich the ma	em. Note: if th anufacturer ha	ne item is an ass as engineering i	sembly with lower responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form T http://www.ipc.org/IPC-175x Distribution			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				als and Mfg Information			
Supplier Information											
Company name* Company unique ID				Unique ID Authority				Response Date*			
nsemi								2024-05-02			
ontact Name Title - Contact				Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative				Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr	fr Item Number Mfr Item Na		Name		te Version		Manufacturing Site		Veight*	UOM	Unit Type
QTe	52012	BBIC6.A0 Tri-Band Adaptive Bas 8x8 + 4x4 to 4x4 (6GHz) + 4x4 +		2024-05-02		,	TWU		23.876	mg	Each
Manufacturing Proccess Information											
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020		STD-020 MSL Rating	Peak Pr	ocess Body T	'emperatu	re Max Time at Peak	Temperatu	are Number	of Reflow Cyc	les	
SnAgCu CU Alloy 3			260		С	30	second	is 3			
Comments											
ATTENTION: MSL 3 Rated item requires Bake a	nd Dry Pack (after	electrical test)									
For more information regarding material composi	tion please refer to	page 3									

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	HS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl thalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	138.921	mg	Supplier	Silicon (Si)	7440-21-3	* *	138.921	mg
Insulating Layer	26.01	mg		Epoxy resin	proprietary data		0.8323	mg
			Supplier	Miscellaneous	Trade Secret		10.8462	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		2.2629	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		9.8058	mg
			Supplier	Formaldehyde Polymer	9003-36-5		2.2629	mg
nsulating Mold	11.0	mg		Hardeness	proprietary data		0.891	mg
			Supplier	1,6-Bis(2,3-epoxypropoxy)naphthalene	27610-48-6		0.2959	mg
			Supplier	Misc.	Proprietary Data		0.2959	mg
			Supplier	Carbon Black (C)	1333-86-4		0.055	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		7.6879	mg
			Supplier	Formaldehyde Polymer	9003-36-5		1.7743	mg
Solder Ball	135.578	mg	Supplier	Silver (Ag)	7440-22-4		4.0673	mg
			Supplier	Tin (Sn)	7440-31-5		130.8328	mg
			Supplier	Copper (Cu)	7440-50-8		0.6779	mg
Solder Mask	20.086	mg		Epoxy resin	proprietary data		7.6327	mg
			Supplier	3-methoxy-3-methylbutylacetate	103429-90-9		2.6112	mg
			Supplier	Miscellaneous	Trade Secret		0.8034	mg
			Supplier	Diethylene glycol monoethyl ether acetate	112-15-2		2.6112	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.0086	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5		1.6069	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		2.812	mg
Substrate - Bump	5.483	mg	Supplier	Silver (Ag)	7440-22-4		0.1645	mg
			Supplier	Tin (Sn)	7440-31-5		5.2911	mg
			Supplier	Copper (Cu)	7440-50-8		0.0274	mg
ubstrate - Core Material	237.037	mg		Other Epoxy resins	proprietary data		71.1111	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		71.1111	mg
			Supplier	Copper (Cu)	7440-50-8		94.8148	mg
ubstrate Plating-Cu	141.406	mg	Supplier	Copper (Cu)	7440-50-8		141.406	mg
Substrate - Plugging	8.355	mg	Supplier	2-Oxiranemethanamine,N-[2-methyl-4- (2-oxiranylmethoxy)phenyl]-N-(2- oxiranylmethyl)	110656-67-2		1.2533	mg

Supplier	Miscellaneous	Trade Secret	3.7597	mg
Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6	2.5065	mg
Supplier	Formaldehyde Polymer	9003-36-5	0.8355	mg